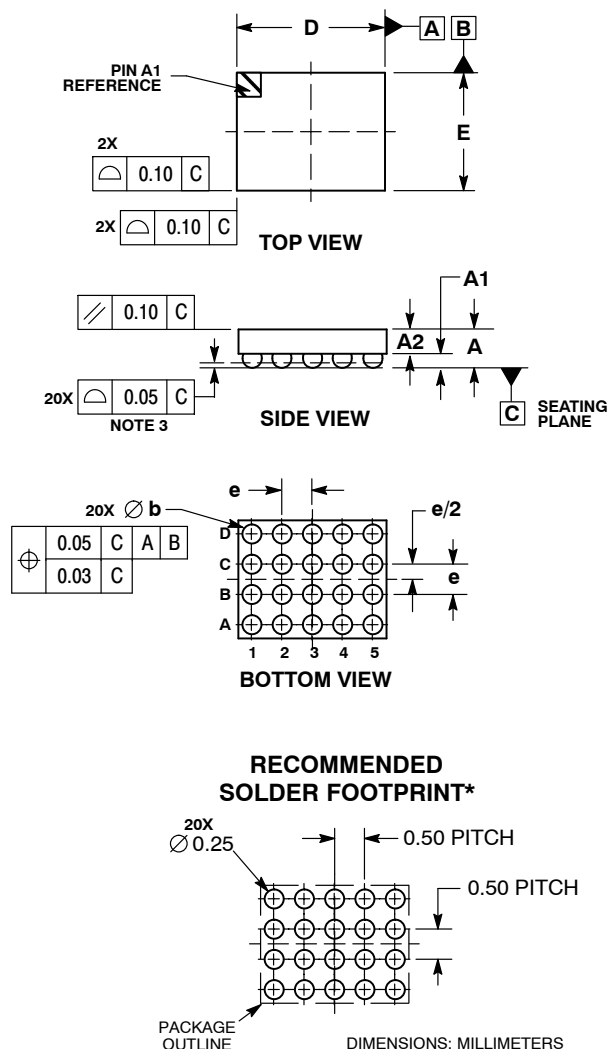



**20 PIN FLIP-CHIP, 2.5x2.0, 0.5P**  
CASE 499BH  
ISSUE A

DATE 22 OCT 2010

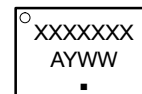
SCALE 4:1



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.
4. DIE COAT, 0.04 THICK, PERMISSABLE ON THIS SURFACE. DIE COAT THICKNESS IS INCLUDED IN DIMENSIONS A AND A2.

| DIM | MILLIMETERS |      |
|-----|-------------|------|
|     | MIN         | MAX  |
| A   | 0.54        | 0.66 |
| A1  | ---         | 0.27 |
| A2  | 0.33        | 0.39 |
| b   | 0.29        | 0.34 |
| D   | 2.50 BSC    |      |
| E   | 2.00 BSC    |      |
| e   | 0.50 BSC    |      |

**GENERIC MARKING DIAGRAM\***


XXXXXXX = Specific Device Code

A = Assembly Location

Y = Year

WW = Work Week

▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, [SOLDERM/D](#).

|                         |  |  |
|-------------------------|--|--|
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| <b>DESCRIPTION:</b>     | <b>20 PIN FLIP-CHIP, 2.5 X 2.0, 0.5P</b> | <b>PAGE 1 OF 1</b>   |

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